# Final Final

# Am27C512

65,536 x 8-Bit CMOS EPROM

T-46-13-29
T- 46-13-25 Advanced
Micro
Devices

#### **DISTINCTIVE CHARACTERISTICS**

- Fast access time -- 70 ns
- · Low power consumption:
- 100 μA maximum standby current
- Programming voltage: 12.5 V

- Single +5-V power supply
- JEDEC-approved pinout
- ±10% power supply tolerance available
- Latch-up protected to 100 mA from -1 V to V<sub>CC</sub> +1 V

#### **GENERAL DESCRIPTION**

The Am27C512 is a 512K-bit, ultraviolet erasable programmable read-only memory. It is organized as 65,536 words by 8 bits per word, operates from a single +5-V supply, has a static standby mode, and features fast single address location programming/ Devices are available in windowed ceramic DIP and LCC packages as well as plastic one time programmable (OTP) packages.

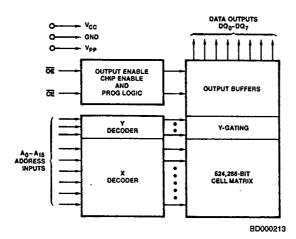
Typically, any byte can be accessed in less than 70 ns, allowing operation with high-performance microprocessors without any WAIT states. The Am27C512 offers separate Output Enable (OE) and Chip Enable (CE) controls, thus

eliminating bus contention in a multiple bus microprocessor system.

AMD's CMOS process technology provides high speed, low power, and high noise immunity. Typical power consumption is only 100 mW in active mode, and 250  $\mu$ W in standby mode.

All signals are TTL levels, including programming signals. Bit locations may be programmed singly, in blocks, or at random. The Am270512 supports AMD's interactive programming algorithm (1-ms pulses).

#### **BLOCK DIAGRAM**



# PRODUCT SELECTOR GUIDE

Family Part No.				Am2	7C512				
Ordering Part No: ±5% Vcc. Tolerance	-75	-95	-125	-155	-175	-205	-255	-305	
±10% V <sub>CC</sub> Tolerance	_	-90	-120	-150	-170	-200	-250	-300	
Max. Access Time (ns)	70	90	120	150	170	200	250	300	
CE (E) Access (ns)	70	90	120	150	170	200	250	300	
OE (G) Access (ns)	40	40	50	50	50	75	100	100	

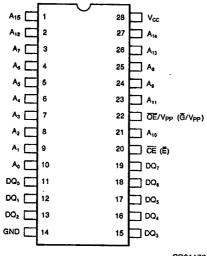
Publication # Rev. Amendment
08140 E /0
Issue Date: November 1989

# CONNECTION DIAGRAMS Top View

T-46-13-29

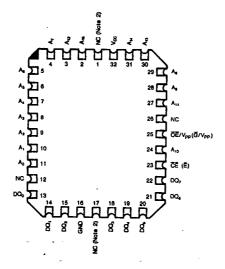
T-46-13-25

DIP



CD011731

LCC\*



CD00600A

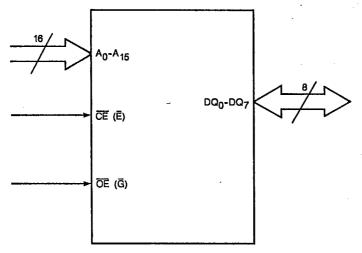
\*Also available in 32-pin rectangular plastic leaded chip carrier.

Notes: 1. JEDEC nomenclature is in parentheses.

2. Don't use (DU) for PLCC.

# LOGIC SYMBOL

T-46-13-29 T-46-13-25



LS003312

#### PIN DESCRIPTION

A<sub>0</sub> - A<sub>15</sub>
CE (E)
DQ<sub>0</sub> - DQ<sub>7</sub>
OE (G)
VCC
VPP
GND
NC
DU

- Address InputsChip Enable Input
- Data Inputs/Outputs
  Output Enable Input
  VCC Supply Voltage
  Program Supply Voltage
- Ground
- No Internal ConnectionNo External Connection

# **ORDERING INFORMATION**

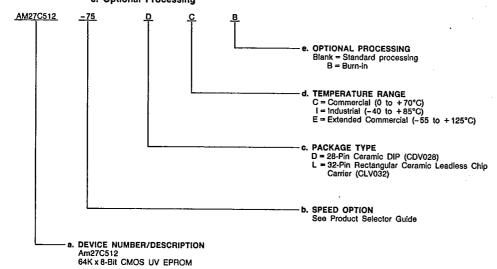
T-46-13-29

# Standard Products

T-46-13-25

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option
- c. Package Type
- d. Temperature Range
- e. Optional Processing



Valid C	ombinations
AM27C512-75	DC, DCB, LC, LCB
AM27C512-95	
AM27C512-125	7
AM27C512-155	
AM27C512-175	DC, DCB, DI, DIB,
AM27C512-205	20, 200, 21, 215
AM27C512-255	_
AM27C512-305	
AM27C512-90	
AM27C512-120	
AM27C512-150	DC, DCB, DI, DIB,
AM27C512-170	DE, DEB, LC, LCB,
AM27C512-200	LI, LIB, LE, LEB
AM27C512-250	7
AM27C512-300	7

# Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

# **ORDERING INFORMATION (Cont'd.)**

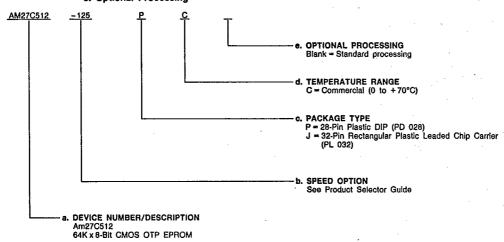
# **OTP Products**

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AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option
- c. Package Type
- d. Temperature Range
- e. Optional Processing



Valid Combinations						
AM27C512-125						
AM27C512-150	7					
AM27C512-155	7					
AM27C512-170	7					
AM27C512-175	7					
AM27C512-200	JC, PC					
AM27C512-205	7					
AM27C512-250	1					
AM27C512-255						
AM27C512-300	7					
AM27C512-305						

#### **Valid Combinations**

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

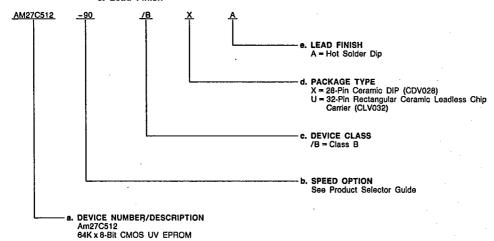
# **MILITARY ORDERING INFORMATION**

#### **APL Products**

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AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option
- c. Device Class
- d. Package Type
- e. Lead Finish



Valid C	Valid Combinations						
AM27C512-90							
AM27C512-120	7						
AM27C512-150							
AM27C512-170	/8XA, /BUA						
AM27C512-200							
AM27C512-250							
AM27C512-300							

#### Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, or to check for newly released valid combinations.

#### **Group A Tests**

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

#### FUNCTIONAL DESCRIPTION

#### Erasing the Am27C512

In order to clear all locations of their programmed contents, it Is necessary to expose the Am27C512 to an ultraviolet light source. A dosage of 15 W seconds/cm<sup>2</sup> is required to completely erase an Am27C512. This dosage can be obtained by exposure to an ultraviolet lamp - wavelength of 2537 Angstroms (Å) — with intensity of 12,000 μW/cm<sup>2</sup> for 15 to 20 minutes. The Am27C512 should be directly under and about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the Am27C512, and similar devices, will erase with light sources having wavelengths shorter than 4000 Å. Although erasure times will be much longer than with UV sources at 2537Å, nevertheless the exposure to fluorescent light and sunlight will eventually erase the Am27C512 and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package window should be covered by an opaque label or substance.

#### Programming the Am27C512

Upon delivery, or after each erasure, the Am27C512 has all 524,288 bits in the "ONE", or HIGH state. "ZEROs" are loaded into the Am27C512 through the procedure of program-

The programming mode is entered when 12.5  $\pm 0.5$  V is applied to the  $\overline{OE}/V_{PP}$  pin, and  $\overline{CE}$  is at V<sub>IL</sub>.

For programming, the data to be programmed is applied 8 bits in parallel to the data output pins.

The flowchart in Figure 1 shows AMD's interactive algorithm. Interactive algorithm reduces programming time by using short programming pulses and giving each address only as many pulses as is necessary in order to reliably program the data. After each pulse is applied to a given address, the data in that address is verified. If the data does not verify, additional pulses are given until it verifies or the maximum is reached. This process is repeated while sequencing through each address of the Am27C512. This part of the algorithm is done at V<sub>CC</sub> = 6.0 V to assure that each EPROM bit is programmed to a sufficiently high threshold voltage. After the interactive programming is completed, an overprogram pulse is given to each memory location; this ensures that all bits have sufficient margin. After the final address is completed, the entire EPROM memory is verified at  $V_{CC} = 5 \text{ V} \pm 5\%$ .

#### Program Inhibit

Programming of multiple Am27C512s in parallel with different data is also easily accomplished. Except for CE, all like inputs of the parallel Am27C512 including OE/Vpp may be common. A TTL low-level program pulse applied to an Am27C512  $\overline{CE}$  input with  $\overline{OE}/Vpp=12.5~\pm~0.5~V$  will program that Am27C512. A high-level  $\overline{CE}$  input inhibits the other Am27C512s from being programmed.

#### Program Verify

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify should be performed with  $\overline{\text{OE}}/\text{Vpp}$  and  $\overline{\text{CE}}$  at  $\text{V}_{\text{IL}}$ . Data should be verified tov after the falling edge of CE

#### **Auto Select Mode**

The auto select mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type.

This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its corresponding programming algorithm. This mode is functional in the 25°C ± 5°C ambient temperature range that is required when programming the Am27C512.

To activate this mode, the programming equipment must force 12.0  $\pm$  0.5 V on address line Ag of the Am27C512. Two identifier bytes may then be sequenced from the device outputs by toggling address line  $A_0$  from  $V_{IL}$  to  $V_{IH}$ . All other address lines must be held at VIL during auto select mode,

Byte 0 ( $A_0 = V_{IL}$ ) represents the manufacturer code, and byte 1 (A<sub>0</sub> = V<sub>IH</sub>), the device identifier code. For the Am27C512, these two identifier bytes are given in the Mode Selector table. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (DQ7) defined as the parity bit.

#### Read Mode

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The Am27C512 has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable (CE) is the power control and should be used for device selection. Output Enable (OE) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (tACC) is equal to the delay from CE to output (tce). Data is available at the outputs toe after the falling edge of OE, assuming that CE has been LOW and addresses have been stable for at least tACC-tOE. T-46-13-25

#### Standby Mode

The Am27C512 has a CMOS standby mode which reduces the maximum VCC current to 100 µA. It is placed in CMOSstandby when  $\overrightarrow{CE}$  is at  $V_{CC} \pm 0.3 \, \text{V}$ . The Am27C512 also has a TTL-standby mode which reduces the maximum V<sub>CC</sub> current to 1.0 mA. It is placed in TTL-standby when  $\overline{\text{CE}}$  is at  $\overline{\text{V}}_{\text{IH}}$ . When in standby mode, the outputs are in a high-impedance state, independent of the OE input.

#### **Output OR-Tieing**

To accomodate multiple memory connections, a two-line control function is provided to allow for:

- 1. Low memory power dissipation, and
- 2. Assurance that output bus contention will not occur.

it is recommended that  $\overline{\text{CE}}$  be decoded and used as the primary device-selecting function, while  $\overline{\text{OE}}/\text{V}_{PP}$  be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

#### System Applications

During the switch between active and standby conditions. transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1-µF ceramic capacitor (high frequency, low inherent inductance) should be used on each device between VCC and GND to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a 4.7-μF bulk electrolytic capacitor should be used between VCC and GND for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

	Pins	MODE SELECT		ILE	(	T-46-13-29		
	- Fills					T-46-13-2		
Mode		CE	OE/V <sub>PP</sub>	A <sub>0</sub>	A <sub>9</sub>	Outputs		
Read		VIL	VIL	х	×	DOUT		
Output Dis	able	V <sub>IL</sub>	VIH	Х	Х	High Z		
Standby (	ITL)	VIH	x	х	×	High Z		
Standby (0	CMOS)	V <sub>CC</sub> ± 0.3 V	X	х	х	High Z		
Program		VIL	Vpp	х	X	DiN		
Program V	ım Verify V <sub>IL</sub>		V <sub>IL</sub> X		х	DOUT		
Program Inhibit		ViH	Vpp	Х	×	High Z		
Auto Select	Manufacturer Code	VIL	V <sub>iL</sub>	V <sub>IL</sub>	V <sub>H</sub>	01 H		
(Note 3)	Device Code	VIL	VIL	V <sub>IH</sub>	VH	91 H		

Notes: 1. X can be either  $V_{IL}$  or  $V_{IH}$ 2.  $V_{H}$  = 12.0 V  $\pm$  0.5 V 3.  $A_{1}$  -  $A_{8}$  =  $A_{10}$  -  $A_{15}$  =  $V_{IL}$ 4. See DC Programming characteristics for  $V_{PP}$  voltage during programming.

# ABSOLUTE MAXIMUM RATINGS

# **OPERATING RANGES**

Storage Temperature:	
OTP devices	65 to 125°C
All other devices	65 to 150°C
Ambient Temperature	
with Power Applied	55 to +125°C
Voltage with Respect to Ground:	
All pins except Ag, Vpp, and	
Vcc	0.6 to V <sub>CC</sub> +0.5 V
Ag and Vpp	0.6 to 13.5 V
V <sub>CC</sub>	0.6 to 7.0 V
<del></del>	

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure of the device to absolute maximum rating conditions for extended periods may affect device reliability.

- Notes: 1. Minimum DC voltage on input or I/O is -0.5 V.
  During transitions, the inputs may undershoot GND to -2.0 V for periods of up to 20 ns. Maximum DC voltage on input and I/O is V<sub>CC</sub> +0.5 V which may overshoot to V<sub>CC</sub> +2.0 V for periods up to 20 ns.
  - For Ag and Vpp the minimum DC input is -0.5 V.
     During transitions, Ag and Vpp may undershoot GND to -2.0 V for periods of up to 20 ns. Ag and Vpp must not exceed 13.5 V for any period of time.

Commercial (C) Devices Case Temperature (T <sub>C</sub> )0 to +70°C
Industrial (I) Devices Case Temperature (T <sub>C</sub> )40 to +85°C
Extended Commercial (E) Devices  Case Temperature (T <sub>C</sub> )
Military (M) Devices Case Temperature (T <sub>C</sub> )55 to +125°C
Supply Read Voltages:  VCC for Am27C512-XX5+4.75 to +5.25 V  VCC for Am27C512-XX0+4.50 to +5.50 V
Operating ranges define those limits between which the functionality of the device is guaranteed.

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DC CHARACTERISTICS over operating range unless otherwise specified (Notes 1, 4, 5 & 7)

TTL and NMOS Inputs

Parameter Symbol	Parameter Description	Test Conc	Min.	Max.	Unit	
VOH	Output HIGH Voltage	$i_{OH} = -400 \mu A$		2.4		٧
VOL	Output LOW Voltage	I <sub>OL</sub> = 2.1 mA			0.45	٠ ٧
ViH	Input HIGH Voltage		2.0	V <sub>CC</sub> + 0.5	٧	
VIL	Input LOW Voltage			-0.3	+0.8	٧
		24 0 24 1- 24	C/I Devices		1.0	μΑ
ILI	Input Load Current VIN = 0 V to VCC	E/M Devices		5.0	μη	
	_	V	C/I Devices		10	μΑ
ILO	Output Leakage Current	V <sub>OUT</sub> = 0 V to V <sub>CC</sub>	E/M Devices		10	μΛ
	V <sub>CC</sub> Active	CE = V <sub>IL</sub> , f = 10 MHz,	C/I Devices		40	mA
ICC1	Current (Note 5 & 8)	lOUT = 0 mA (Open Outputs)	E/M Devices		50	(10)
	Vcc Standby Current	CE = VIH,	C/I Devices		1	mA
ICC2	(Note 8)	OE = VIL	E/M Devices		1	. 1117

**CMOS** inputs

Parameter Symbol	Parameter Description	Test Cor	Min.	Max.	Unit	
Voн	Output HIGH Voltage	I <sub>OH</sub> = -400 μA	2.4		٧	
VOL	Output LOW Voltage	I <sub>OL</sub> = 2.1 mA			0.45	٧
ViH	Input HIGH Voltage			VCC-0.3	V <sub>CC</sub> + 0.3	٧
ViL	Input LOW Voltage			-0.3	+0,8	V
		V 04 - V	C/I Devices		1.0	
ILI Inpi	Input Load Current	V <sub>IN</sub> = 0 V to V <sub>CC</sub>	E/M Devices		5.0	μΑ

DC CHARACTERISTICS over operating range unless otherwise specified (Cont'd.)

**CMOS** Inputs

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Parameter Symbol	Parameter Description	Test Con	Min.	Max.	Unit	
li o	Output Leakage Current	Vout = 0 V to Vcc	C/I Devices		10	
/LO	Output Leakage Current	A001 - 0 A 10 ACC	E/M Devices			μΑ
loc <sub>1</sub>	V <sub>CC</sub> Active	CE = V <sub>IL</sub> , f = 10 MHz,	C/I Devices		40	mA
	Current (Note 5 & 8)	IOUT = 0 mA (Open Outputs)	E/M Devices		50	
ICC2	V <sub>CC</sub> Standby Current	CE = V <sub>CC</sub> ± 0.3 V	C/I Devices		100	
	(Note 8)	OE - 4CC + 0.3 4	E/M Devices		100	μΑ

#### CAPACITANCE (Notes 2, 3, & 6)

Parameter Symbol	Parameter Description	Test Conditions	Max.	Unit	
C <sub>IN1</sub>	Input Capacitance	V <sub>IN</sub> = 0 V	10	pF	
C <sub>IN2</sub>	OE/Vpp Input Capacitance	V <sub>IN</sub> = 0 V	12	ρF	
CIN3	CE Input Capacitance	V <sub>IN</sub> = 0 V	10	pF	
COUT	Output Capacitance	V <sub>OUT</sub> = 0 V	12	pF	

Notes: 1. V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub>, and removed simultaneously or after V<sub>PP</sub>.

2. Typical values are for nominal supply voltages.

3. This parameter is only sampled and not 100% tested.

4. Caution: The Am27C512 must not be removed from, or inserted into, a socket or board when V<sub>PP</sub> or V<sub>CC</sub> is applied.

5. I<sub>CC</sub>1 is tested with OE = V<sub>IH</sub> to simulate open outputs.

6. T<sub>A</sub> = 25°C, f = 1 MHz.

7. Minimum DC input voltage is -0.5 V. During transitions, the inputs may undershoot to -2.0 V for periods less than 20 ns.

Maximum DC voltage on output pins is V<sub>CC</sub> +0.5 V which may overshoot to V<sub>CC</sub> +2.0 V for periods less than 20 ns.

8. For Am27C512-305DC I<sub>CC1</sub> = 50 mA, I<sub>CC2</sub> (TTL) = 5 mA, I<sub>CC2</sub> (CMOS) = 500 μA maximum.

# SWITCHING CHARACTERISTICS over operating ranges unless otherwise specified (Notes 1, 3, & 4)

Parameter Symbols						Am27C512							
JEDEC	Standard	Parameter Description	Test Conditions		- -75	-90, -95	-120, -125	-150, -155	-170, -175	-200, -205	-250, -255	-300, -305	Unit
tavov tacc Address to O	Address to Output	CE = OE/Vpp = ViL	Min.								Ì		
AVQV	'ACC	Delay	CE - CE/VPP - VIL	Max.	70	90	120	150	170	200	250	300	ns
tELQV	tCE	Chip Enable to	OE/Vpp = V <sub>IL</sub>	Min.									
-CLGA	- CE	Output Delay		Max.	70	90	120	150	170	200	250	300	ns
tg.cov	tgLQV toE Output Enable to	CE = VIL Min.											
*GLGV	402	Output Delay	OE - VIL	Max.	40	40	50	50	50	75	100	100	ns
tEHQZ,	tor	Output Enable HIGH to Output		Min.									
tGHQZ IDF	Float (Note 2)		Max.	25	30	30	30	30	60	60	60	ns	
	Output Hold from Addresses, CE, or		Min.	0	0	0	0	0	0	0	0		
-70.00	_ 5A	OE,whichever occurred first		Max									ns

Notes: 1.  $V_{CC}$  must be applied simultaneously or before  $V_{PP}$ , and removed simultaneously or after  $V_{PP}$ .

2. This parameter is only sampled and not 100% tested.

3. Caution: The Am27C512 must not be removed from, or inserted into, a socket or board when Vpp or Vcc is applied.

For the Am27C512-75:

Output Load: 1 TTL gate and C<sub>L</sub> = 30 pF, input Rise an Fall Times: 20 ns, input Pulse Levels: 0 to 3 V,

Timing Measurement Reference Level: 1.5 V for inputs and outputs.

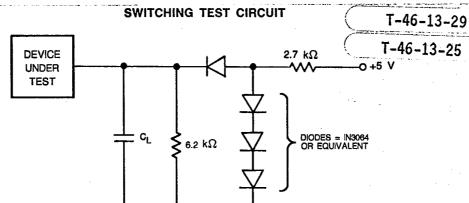
For all other versions:

Output Load: 1 TTL gate and CL = 100 pF,

Input Rise and Fall Times: 20 ns.

Input Pulse Levels: 0.45 to 2.4 V,

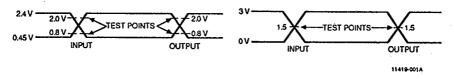
Timing Measurement Reference Level: 0.8 V and 2 V for inputs and outputs.



 $C_L = 100$  pF including jig capacitance (30 pF for -75)

TC003193

# SWITCHING TEST WAVEFORM



WF026840

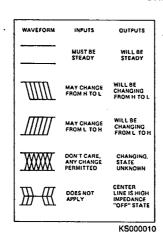
AC Testing: Inputs are driven at 2.4 V for a logic "1" and 0.45 V for a logic "0". Input pulse rise and fall times are ≤20 ns.

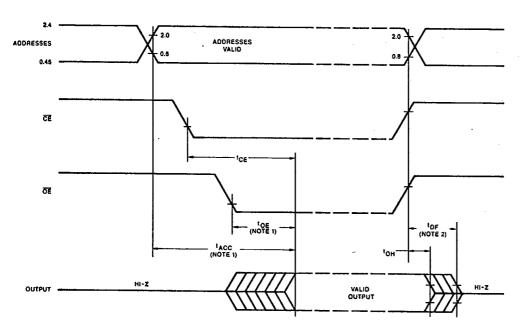
AC Testing: Inputs are driven at 3.0 V for a logic "1" and 0 V for a logic "0". Input pulse rise and fall times are ≤20 ns for -75 devices.

# SWITCHING WAVEFORMS

# **KEY TO SWITCHING WAVEFORMS**

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WF001323

Notes: 1.  $\overline{OE}$  may be delayed up to  $t_{ACC}$  -  $t_{OE}$  after the falling edge of  $\overline{CE}$  without impact on  $t_{ACC}$ .

2.  $t_{DF}$  is specified from  $\overline{OE}$  or  $\overline{CE}$ , whichever occurs first.

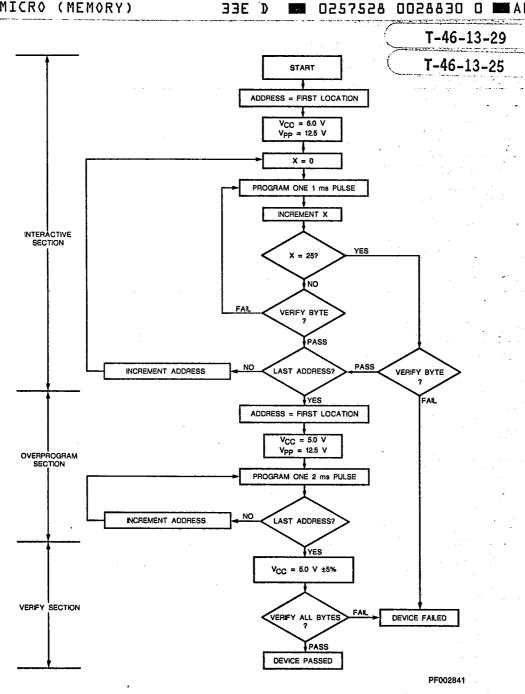


Figure 1. Interactive Programming Flow Chart

# INTERACTIVE ALGORITHM

DC PROGRAMMING CHARACTERISTICS ( $T_A = +25$ °C  $\pm 5$ °C) (Notes 1, 2, & 3).

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Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
lu	Input Current (All Inputs)	VIN = VIL or VIH		10.0	μΑ
V <sub>IL</sub>	Input LOW Level (All Inputs)		-0.3	0.8	
V <sub>IH</sub>	Input HIGH Level		2.0	V <sub>CC</sub> + 0.5	·
V <sub>OL</sub>	Output LOW Voltage During Verify	I <sub>OL</sub> = 2.1 mA		0.45	v
VoH	Output HIGH Voltage During Verify	I <sub>OH</sub> = -400 μA	2,4		<u>·</u>
VH	Ag Auto Select Voltage		11.5	12.5	
Іссз	V <sub>CC</sub> Supply Current (Program & Verify)		•	50	mA
Ірр	Vpp Supply Current (Program)	CE = VIL, OE/Vpp = Vpp		30	mA
Vcc	Interactive Supply Voltage		5.75	6.25	
Vpp	Interactive Programming Voltage		12.0	13.0	<del></del>

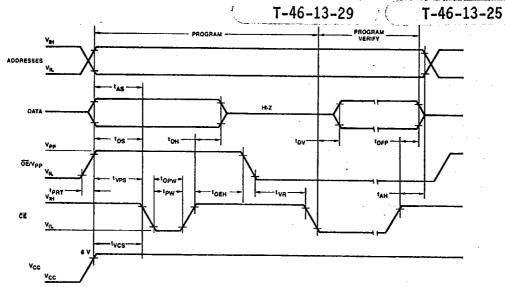
# SWITCHING PROGRAMMING CHARACTERISTICS ( $T_A = +25$ °C ±5°C) (Notes 1, 2, & 3).

Parameter Symbols					
JEDEC	Standard	Parameter Description	Min.	Max.	Uni
<sup>†</sup> AVEL	tas	Address Setup Time	2	, , , , , , , , , , , , , , , , , , ,	με
†DVEL	tos	Data Setup Time	2		με
<sup>t</sup> GHAX	t <sub>AH</sub>	Address Hold Time	0		μ
<sup>t</sup> EHDX	t <sub>DH</sub>	Data Hold Time	2		με
t <sub>EHQZ</sub>	tDFP	Chip Enable to Output Float Delay	0	60	ns
typs	tvps	Vpp Setup Time	2		με
telen1	tpw	CE Initial Program Pulse Width	0.95	1.05	ms
tELEH2	topw	CE Overprogram Pulse Width	1.95	2.05	ms
tvcs	tvcs	V <sub>CC</sub> Setup Time	2		μs
t <sub>ELQV</sub>	tov	Data Valid from CE	<del>  </del> -	250	ns
tengL	<sup>t</sup> OEH	ÕE/V <sub>PP</sub> Hold Time	2		μs
tGLEL .	tvR	OE/Vpp Recovery Time	2		μs

Notes: 1. V<sub>CC</sub> must be applied simultaneously or before V<sub>PP</sub>, and removed simultaneously or after V<sub>PP</sub>.

2. When programming the Am27C512, a 0.1-μF capacitor is required across V<sub>PP</sub> and ground to suppress spurious voltage transients which may damage the device.

3. Programming characteristics are sampled but not 100% tested at worst-case conditions.



WF021992

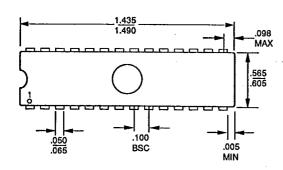
Notes: 1. The input timing reference level is 0.8 V for V<sub>IL</sub> and 2 V for V<sub>IH</sub>.

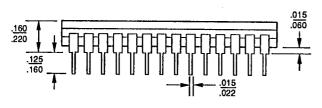
2. toe and toep are characteristics of the device, but must be accommodated by the programmer.

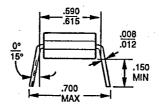
# PHYSICAL DIMENSIONS

# **CDV**028

T-46-13-29 T-46-13-25

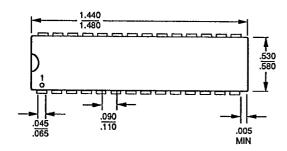


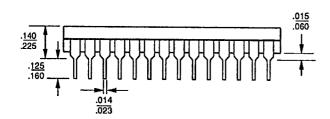


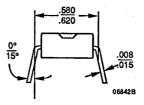


PD 028

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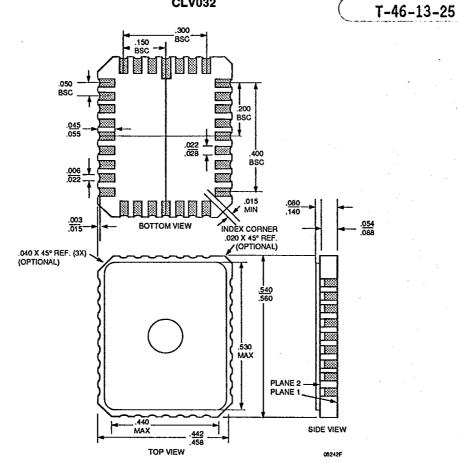




PHYSICAL DIMENSIONS (Cont'd.)

**CLV**032

T-46-13-29



PL 032

